

IN THE CLAIMS

Claims 1-12 and 16-2: 1 Canceled.

13. (Currently Amended) A method for coupling an IC to a supporting surface comprising:
- providing an IC;
 - providing a supporting surface to which the IC is to be mechanically and electrically bonded;
 - providing a pre-form assembly comprising a base layer and a sacrificial assembly, the base layer comprising a thermosetting material or a thermoplastic material and wire or solder paste through conductors and the sacrificial assembly comprising a sacrificial layer and a release coating, wherein the release coating is located between the sacrificial layer and the base layer;
 - applying the pre-form assembly to either the IC or supporting surface;
 - removing at least part of the sacrificial assembly, wherein removal of at least part of the sacrificial assembly comprises destruction of the layer during the curing of the base layer;
 - sandwiching the base layer between the IC and the supporting surface; and
 - curing the base layer.
14. (Previously Presented) The method of claim 13 wherein providing the preform assembly comprises:
- providing a sacrificial layer;
 - coating the sacrificial layer with a release coating to form a sacrificial assembly;
 - applying a thermosetting material on top of the release coating;
 - curing the thermosetting material to form a B-stage layer; and

inserting through conductors into the thermosetting material.

15. (Original) The method of claim 14 wherein the step of inserting through conductors into the thermosetting material comprises either piercing wires into the thermosetting material, or lasing or drilling and subsequently filling holes in the thermosetting material with a solder paste.
22. (Previously Presented) The method of claim 14 wherein the release coating at least partially comprises silicon, polytetrafluoroethylene, or graphite release agents.
23. (Previously Presented) The method of claim 13 wherein the base layer further comprises a fine mesh fiber material impregnated with the thermosetting material, and the fine mesh fiber is thermally conductive.
24. (Previously Presented) The method of claim 13 wherein the base layer further comprises a fine mesh fiber material impregnated with the thermosetting material and the fine mesh fiber is electrically non-conductive.
25. (Previously Presented) The method of claim 13 wherein the base layer further comprises the thermosetting material intermixed with a particle filler.
26. (Previously Presented) The method of claim 25 wherein the particle filler is thermally conductive.
27. (Previously Presented) The method of claim 25 wherein the particle filler is electrically non-conductive.
28. (Previously Presented) The method of claim 13, wherein the sacrificial layer comprises polyester or a celluloid film.

Claim 29: Canceled.